L Number	Hits	Search Text	DB	Time of
1	3434	(chip adj1 chip) and (wire wiring) and	USPAT;	Time stamp 2003/02/12 15:45
		(substrate (printed adj circuit adj board))	US-PGPUB; EPO; JPO;	2003/02/12 13.43
2	7666	(qfp qfn ((flat quad) near1 package))	DERWENT USPAT; US-PGPUB;	2003/02/12 15:44
3	18209	//250 252 //5124	EPO; JPO; DERWENT	
	10209	((qfp qfn ((flat quad) nearl package))) (chip adj1 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 15:45
4	5380	(((qfp qfn ((flat quad) nearl package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO;	2003/02/12 15:46
5	138299	(first near1 (package die chip device))	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/02/12 15:48
6	1691	<pre>((((qfp qfn ((flat quad) nearl package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first nearl (package die chip device)))</pre>	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:07
7	1441	(((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:08
8	939	chip device)))) and (mounting mounted) ((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:08
9	432	((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and (test testing tested)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:09
10	170	((((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board)) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and (test testing tested)) and pad and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:12
	- 31 -	<pre>(((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and pad and electrode</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:10
12		<pre>((((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and pad and electrode) and semiconductor</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:15

13	140	11111111111 of n of n 1163-4 1		
1 10	1 140	/ ((((((((dap dan ((trac daga) near)	USPAT;	2003/02/12 16:21
	- 3	package))) (chip adj1 chip)) and (wire	US-PGPUB;	
		wiring) and (substrate (printed adj	EPO; JPO;	
		circuit adj board))) and ((first near1	DERWENT	
		(package die chip device)))) and (mounting		
		mounted)) and (sealed sealing encapsulant		
		encapsulating encapsulated)) and pad and		
		electrode) and semiconductor) not (bum		
		ball)		
14	218	(((((((qfp qfn ((flat quad) near1	USPAT;	2003/02/12 16:21
		package))) (chip adj1 chip)) and (wire	US-PGPUB;	
		wiring) and (substrate (printed adj	EPO; JPO;	-
		circuit adj board))) and ((first near1	DERWENT	
		(package die chip device)))) and (mounting		
		mounted)) and (sealed sealing encapsulant		
		encapsulating encapsulated)) and pad and		·
		electrode) not ((((((((qfp qfn ((flat		
		quad) near1 package))) (chip adj1 chip))		
		and (wire wiring) and (substrate (printed		
		adj circuit adj board))) and ((first near1		
		(package die chip device)))) and (mounting		
		mounted)) and (sealed sealing encapsulant		
		encapsulating encapsulated)) and pad and		
		electrode) and semiconductor) not (bum		
1.5	_	ball))		
15	7	("5181097" "5665795" "5683942"	USPAT	2003/02/12 16:28
		"5708300" "5726489" "5729051"		
]	"5841192").PN.		